1 Characteristics

Table 1. Absolute ratings (limiting values at 25° C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			1000	V
$I_{F(RMS)}$	RMS forward current			50	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$	TO-220 / DO-247	T_c = 105° C	30	A
		DOP3I	T_c = 65° C		
I_{FRM}	Repetitive peak forward current	t_p = 5 µs, F = 5 kHz square		300	A
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms Sinusoidal		180	A
T_{stg}	Storage temperature range			-65 to + 175	°C
T_j	Maximum operating junction temperature			175	°C

Table 2. Thermal parameters

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220 / DO-247	1.1	°C/W
		DOP3I	1.8	

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
I_R(1)	Reverse leakage current	T_j = 25° C	$V_R = V_{RRM}$			15	µA
		T_j = 125° C			10	100	
V_F(2)	Forward voltage drop	T_j = 25° C	I_F = 30 A			2	V
		T_j = 100° C			1.4	1.8	
		T_j = 150° C			1.3	1.7	

1. Pulse test: t_p = 5 ms, δ < 2 %
2. Pulse test: t_p = 380 µs, δ < 2 %

To evaluate the conduction losses use the following equation:
$P = 1.3 \times I_{F(AV)} + 0.013\ I_F{}^2{}_{(RMS)}$

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
t_{rr}	Reverse recovery time	I_F = 1 A, dI_F/dt = -50 A/µs, V_R = 30 V, T_j = 25° C			100	ns
		I_F = 1 A, dI_F/dt = -100 A/µs, V_R = 30 V, T_j = 25° C		53	70	
		I_F = 1 A, dI_F/dt = -200 A/µs, V_R = 30 V, T_j = 25° C		42	55	
I_{RM}	Reverse recovery current	I_F = 30 A, dI_F/dt = -200 A/µs, V_R = 600 V, T_j = 125° C		24	32	A
S	Softness factor	I_F = 30 A, dI_F/dt = -200 A/µs, V_R = 600 V, T_j = 125° C		1		
t_{fr}	Forward recovery time	I_F = 30 A dI_F/dt = 100 A/µs V_{FR} = 1.5 x V_{Fmax}, T_j = 25° C			450	ns
V_{FP}	Forward recovery voltage	I_F = 30 A, dI_F/dt = 100 A/µs, T_j = 25° C		5		V

Figure 1. Conduction losses versus average current

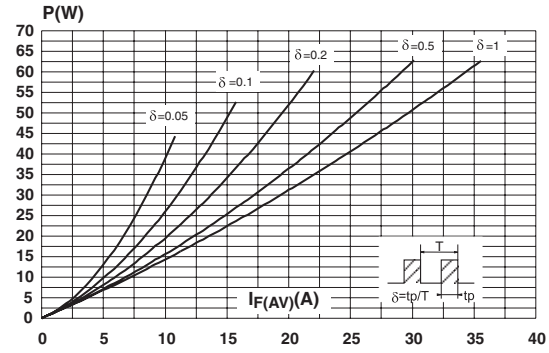


Figure 2. Forward voltage drop versus forward current

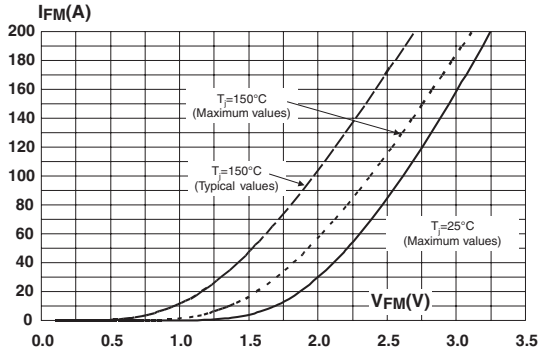


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

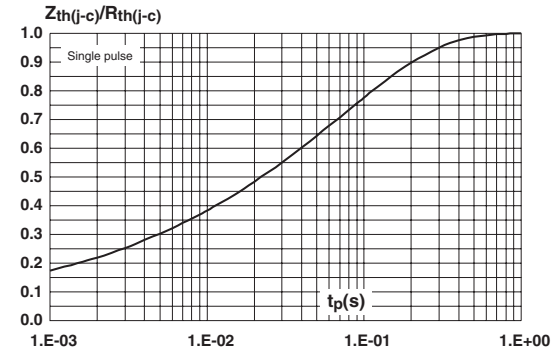


Figure 4. Peak reverse recovery current versus dI_F/dt (typical values)

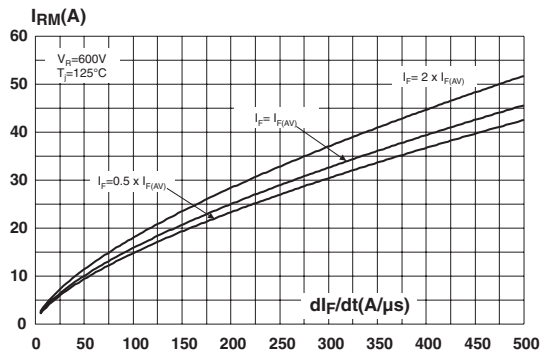


Figure 5. Reverse recovery time versus dI_F/dt (typical values)

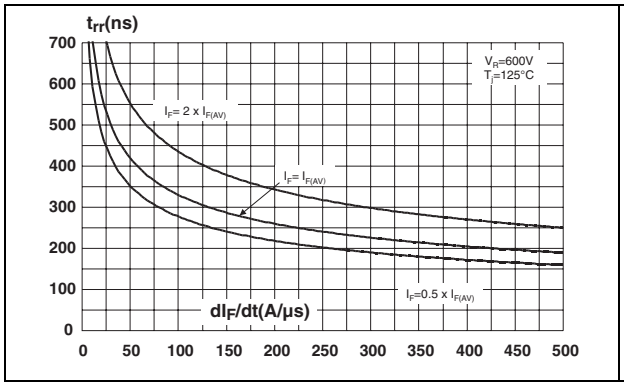


Figure 6. Reverse recovery charges versus dI_F/dt (typical values)

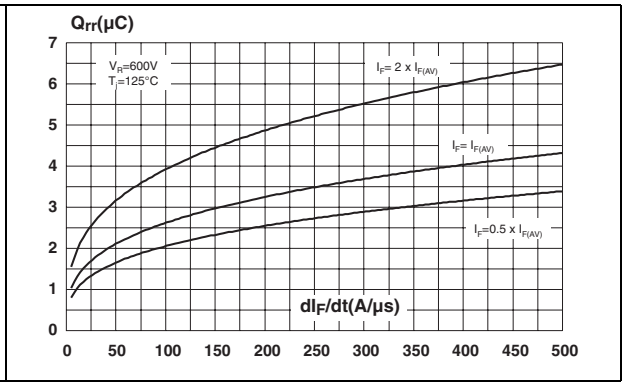


Figure 7. Softness factor versus dI_F/dt (typical values)

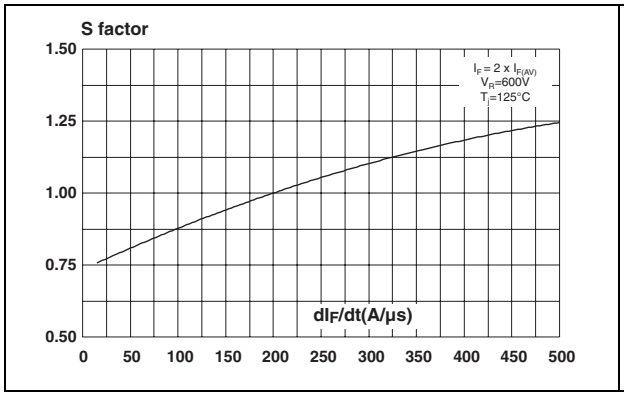


Figure 8. Relative variations of dynamic parameters versus junction temperature

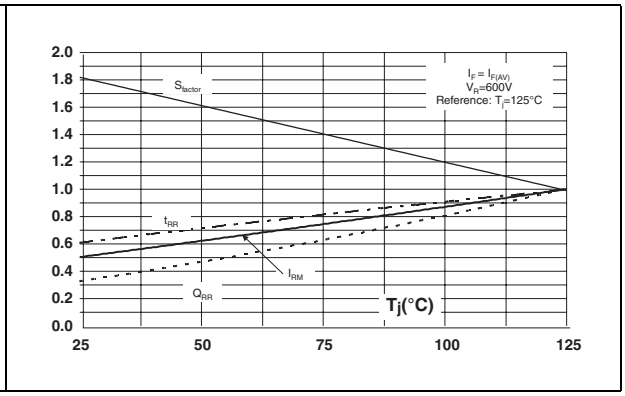


Figure 9. Transient peak forward voltage versus dI_F/dt (typical values)

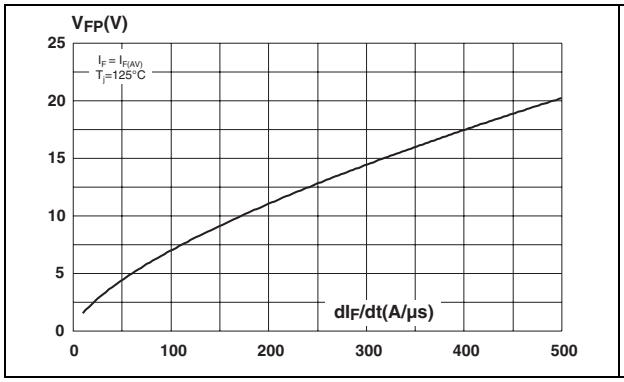


Figure 10. Forward recovery time versus dI_F/dt (typical values)

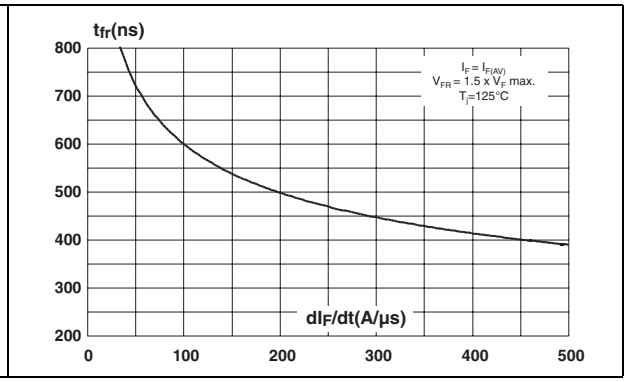
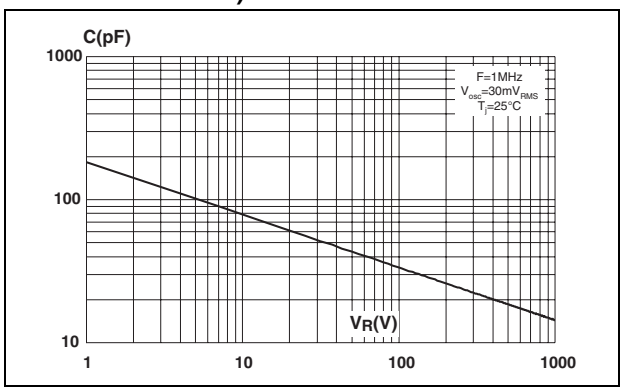


Figure 11. Junction capacitance versus reverse voltage applied (typical values)



2 Package information

Epoxy meets UL94, V0

Cooling method: by conduction (C)

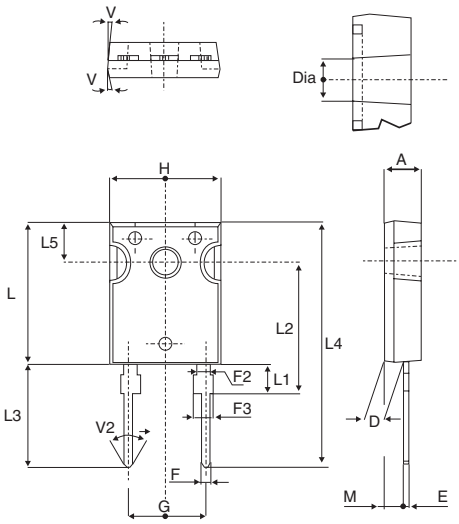
Recommended torque value: 0.55 Nm (TO-220AC)

Recommended torque value: 0.80 Nm (SOD93, DOP31, and DO-247)

Maximum torque value: 0.7 Nm (TO-220AC)

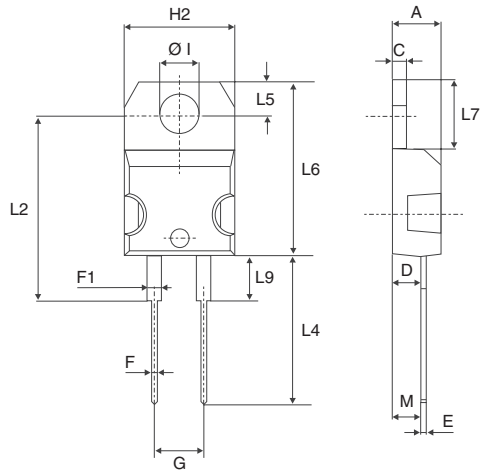
Maximum torque value: 1.0 Nm (SOD93, DOP31, and DO-247)

Table 5. DO-247 dimensions



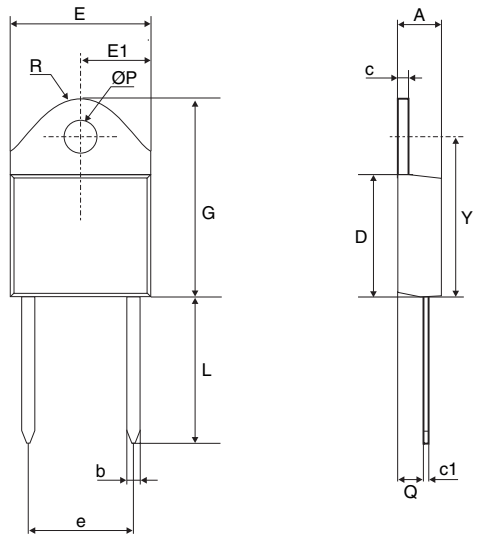
REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.		Max	Min.		Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

Table 6. T0-220AC dimensions



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

Table 7. DOP3I dimensions



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	1.20	1.40	0.047	0.055
c	1.45	1.55	0.057	0.061
c1	0.50	0.70	0.020	0.028
D	12.15	13.10	0.474	0.516
E	15.10	15.50	0.594	0.610
E1	7.55	7.75	0.297	0.305
e	10.80	11.30	0.425	0.445
G	20.4	21.10	0.815	0.831
L	14.35	15.60	0.565	0.614
P	4.08	4.17	0.161	0.164
Q	2.70	2.90	0.106	0.114
R	4.60 typ.		0.181 typ.	
Y	15.80	16.50	0.622	0.650

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

3 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
STTH3010D	STTH3010D	TO-220AC	1.86 g	50	Tube
STTH3010PI	STTH3010PI	DOP3I	4.46 g	30	Tube
STTH3010W	STTH3010W	DO-247	4.4 g	30	Tube

4 Revision history

Date	Revision	Description of Changes
02-Mar-2006	1	First issue.

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